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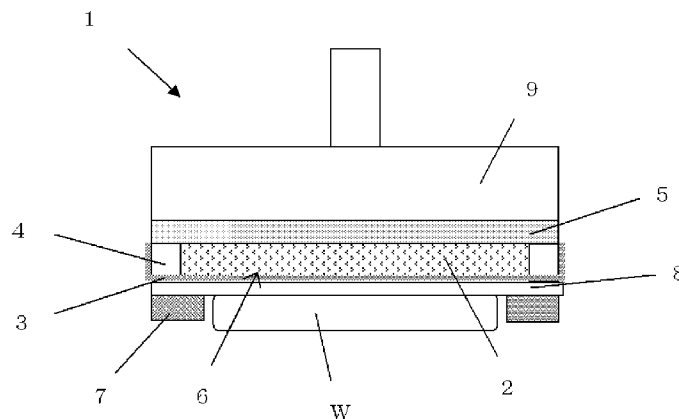
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(54) Title: POLISHING HEAD AND POLISHING APPARATUS

(54) 発明の名称: 研磨ヘッド及び研磨装置

【図1】



(57) Abstract: The present invention is a polishing head which is provided with at least: an annular rigid ring; a rubber film that is bonded to the rigid ring at a uniform tension; a back plate that is joined to the rigid ring so as to form a space together with the rubber film and the rigid ring; and an annular template that is arranged concentrically with the rigid ring in the periphery of the lower surface portion of the rubber film and holds an edge portion of a workpiece. The polishing head polishes the front surface of the workpiece by holding the back surface of the workpiece in the lower surface portion of the rubber film and bringing the front surface of the workpiece in slide contact with a polishing cloth that is bonded to a polishing plate. The polishing head is characterized by additionally comprising a non-compressible fluid that is sealed in the above-described space. Consequently, final polishing of a workpiece can be performed and the entire of the workpiece can be uniformly polished regardless of the thickness of a template by a polishing head that holds the back surface of the workpiece at a rubber film, while holding the edge portion of the workpiece with the template. The present invention also provides a polishing apparatus.

(57) 要約:

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WO 2013/001719 A1